Quarterly Reliability Monitoring Results

Quarters: Q3/2021 to Q4/2022

Based on structural similarity

Supplier	User Part Number
Nexperia B.V.	PMEG4002AESF
Name of Laboratory	**Part Description**
Assembly reliability labs	Nexperia DHAM BD Schottky

Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects
# 1	**TEST** Pre- and Post-Stress Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below
# 5	**HTRB** High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage[1]	1000 hours	51	3080	0
# 7	**TC** Temperature Cycling	JESD22-A104 -40 °C to 125°C	1000 cycles	51	3080	0
# 8 **or**	**UHAST** Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %	96 hours	n.a.	n.a.	n.a.
# 8a	**AC** Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)				
# 9	**H3TRB** High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage[1], [2]	1000 hours	n.a.	n.a.	n.a.
# 10	**IOL** Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles	1000 hours	51	3080	0
# 20	**RSH** Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.
# 21	**SD** Solderability	J-STD-002		42	420	0

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5)
Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Schottky	3080	0	1,38	7,25E+08

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